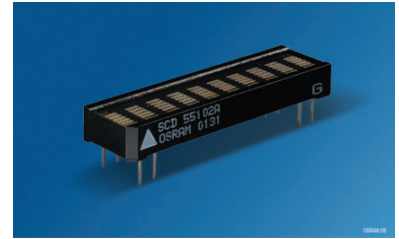


## 0.145" 10-Character 5x5 Dot Matrix Serial Input Dot Addressable Intelligent Display® Devices

### Lead (Pb) Free Product - RoHS Compliant

Standard Red	SCD55100A
Yellow	SCD55101A
High Efficiency Red	SCD55102A
Green	SCD55103A
High Efficiency Green	SCD55104A



## *Slimline*

### DESCRIPTION

The SCD55100A (Red), SCD55101A (Yellow), SCD55102A (HER), SCD55103A (Green) and SCD55104A (HEG) are eight digit dot addressable 5 x 5 matrix, Serial Input, Intelligent Display devices.

The ten 3.68 mm (0.145") high digits are packaged in a rugged, high quality optically transparent, standard 7.62 mm (0.3") pin spacing 28 pin plastic DIP.

The on-board CMOS has a 250 bit RAM, one bit associated with one LED, each to generate User Defined Characters. Due to the reduced LED count, power requirement and heat dissipation are reduced by 30%. Additionally in Power Down Mode quiescent current is <math>< 50 \mu\text{A}</math>.

The SCD5510XA is designed to work with the Serial port of most common microprocessors. The multiplex Clock I/O (CLK I/O) and multiplex Clock Select ( $\overline{\text{CLKSEL}}$ ) pins offer the user the capability to supply a high speed external multiplex clock. This feature can minimize audio in-band interference for portable communication equipment or eliminate the visual synchronization effects found in high vibration environments such as avionics equipment.

### FEATURES

- Low Profile Package: 60% Smaller than Industry Standard 10-Digit Display
- Ten 3.68 mm (0.145") 5 x 5 Dot Matrix Characters in Red, Yellow, High Efficiency Red, Green, or High Efficiency Green
- Optimum Display Surface Efficiency (display area to package ratio)
- Low Power—30% Less Power Dissipation than 5 x 7 Format
- High Speed Data Input Rate: 5.0 MHz
- ROMless Serial Input, Dot Addressable Display—Ideal for User Defined Characters
- Built-in Decoders, Multiplexers and LED Drivers
- Readable from 1.8 meters (6 Feet)
- Wide Viewing Angle, X Axis  $\pm 55^\circ$ , Y Axis  $\pm 65^\circ$
- Attributes:
  - 250 bit RAM for User Defined Characters
  - Eight Dimming Levels
  - Power Down Mode (<math>< 250 \mu\text{W}</math>)
  - Hardware/Software Clear Function
  - Lamp Test
- Internal or External Clock
- End-Stackable Dual-in-line Plastic Package
  - 3.3 V Capability

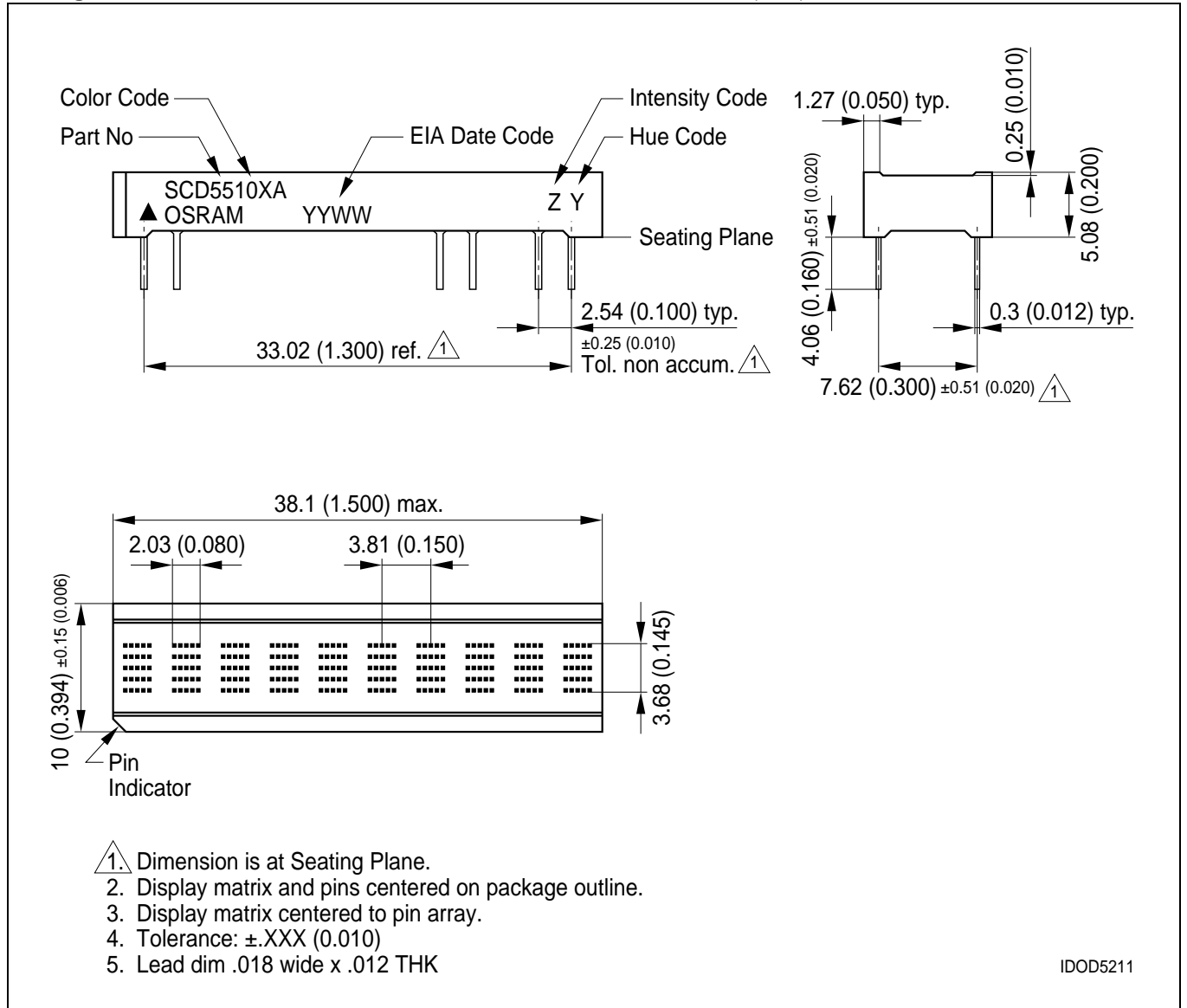
# SCD55100A, SCD55101A, SCD55102A, SCD55103A, SCD55104A

## Ordering Information

Type	Color of Emission	Character Height mm (inch)	Ordering Code
SCD55104A	standard red	3.68 (0.145)	Q68100A0988
SCD55101A	yellow		Q68100A0989
SCD55102A	high efficiency red		Q68100A0990
SCD55103A	green		Q68100A0991
SCD55104A	high efficiency green		Q68100A0992

## Package Outlines

Dimensions in mm (inch)



**Maximum Ratings**

Parameter	Symbol	Value	Unit
Operating temperature range	$T_{op}$	- 40 ... + 85	°C
Storage temperature range	$T_{stg}$	- 40 ... + 100	°C
DC Supply Voltage	$V_{CC}$	-0.5 to + 7.0	V
Input Voltage Levels Relative to GND		-0.5 to $V_{CC}$ to 0.5	V
Solder Temperature 1.59 mm (0.063") below seating plane, t < 5.0 s	$T_s$	260	°C
Relative Humidity		85	%
ESD (100 pF, 1.5 kΩ)	$V_z$	2.0	kV
Input Current		± 100	mA
Power Dissipation at 85°C		1.7	W
Maximum Number of LEDs on at 100% Brightness		160	
IC Junction Temperature		125	°C

**Optical Characteristics at 25°C**

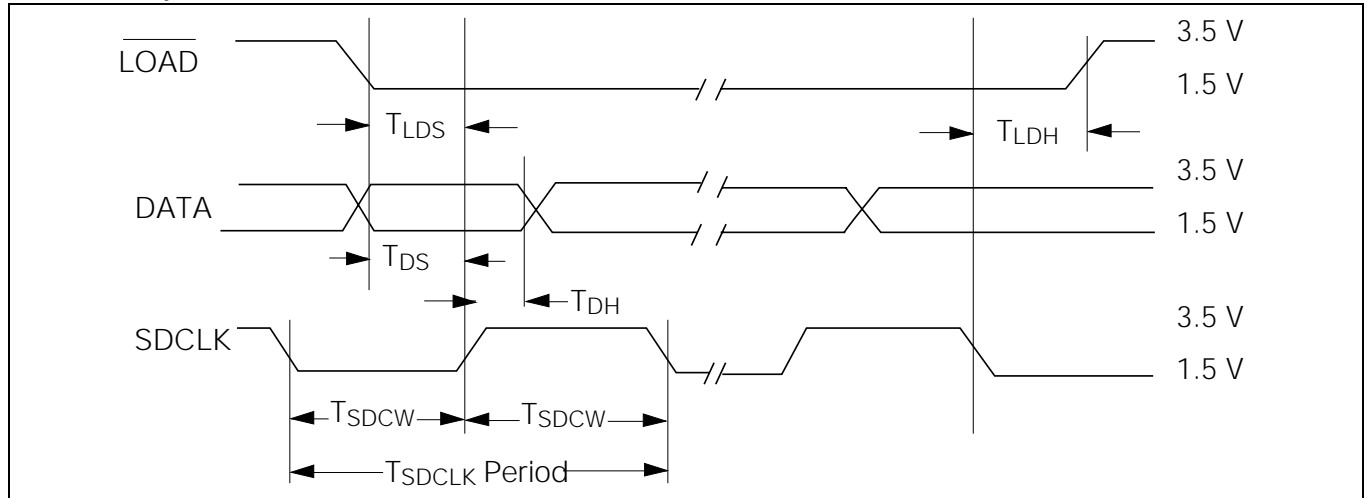
( $V_{CC}$ =5.0 V at 100% brightness level, viewing angle: X axis ± 55°, Y axis ± 65°)

Description	Symbol	Values					Unit
		Red SCD55100A	Yellow SCD55101A	High Efficiency Red SCD55102A	Green SCD55103A	High Efficiency Green SCD55104A	
Luminous Intensity (min.) (typ.)	$I_v$	36 78	124 208	124 237	124 238	124 500	μcd/dot μcd/dot
Peak Wavelength (typ.)	$\lambda_{peak}$	665	583	630	565	568	nm
Dominant Wavelength (typ.)	$\lambda_{dom}$	639	584	626	569	572	nm

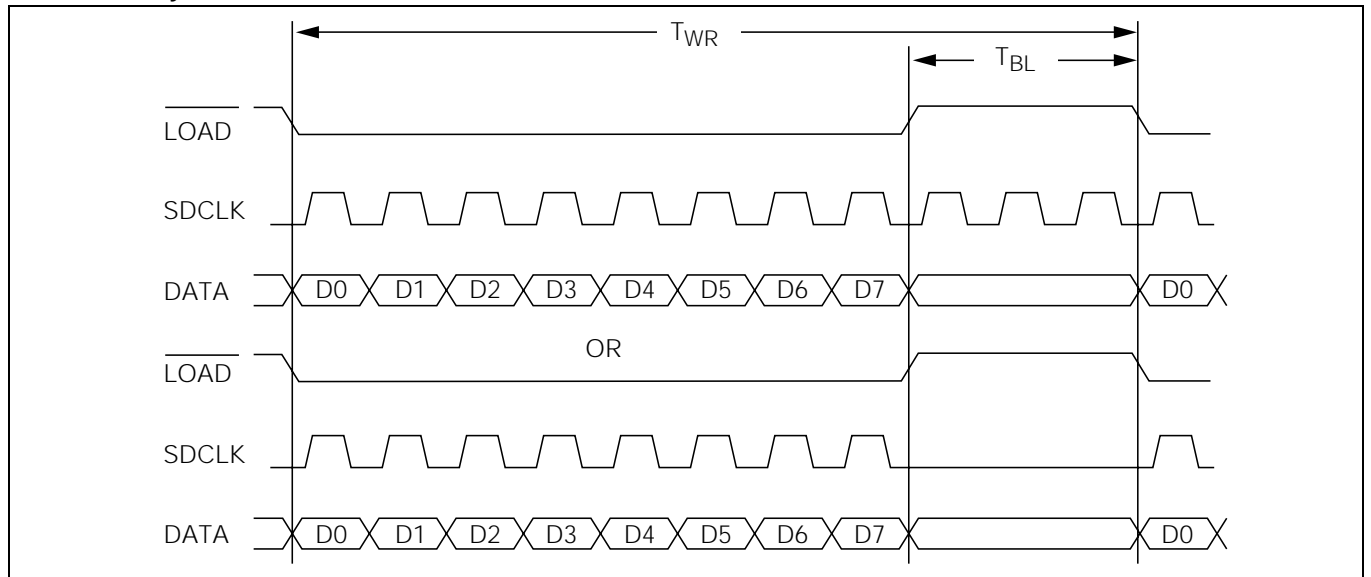
Notes:

1. Dot to dot intensity matching at 100% brightness is 1.8:1.
2. Displays are binned for hue at 2.0 nm intervals.
3. Displays within a given intensity category have an intensity matching of 1.5:1 (max.).

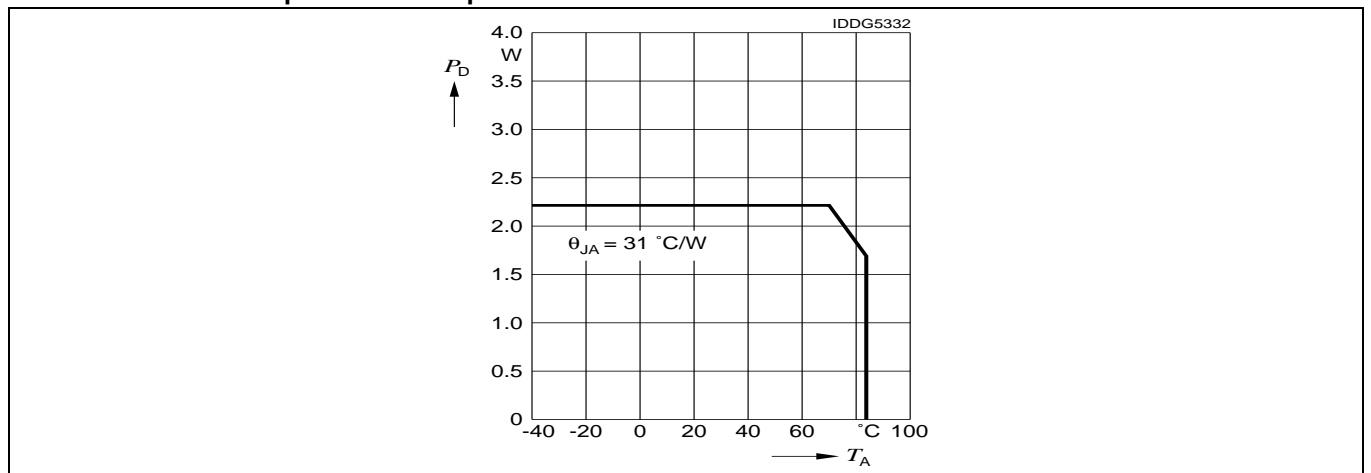
Data Write Cycle



Instruction Cycle



Maximum Power Dissipation vs. Temperature



## Electrical Characteristics (over operating temperature)

Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{CC}$	4.5	5.0	5.5	V	—
$I_{CC}$ (Pwr Dwn Mode) <sup>(4)</sup>	—	50	—	$\mu$ A	$V_{CC}=5.0$ V, all inputs=0 V or $V_{CC}$
$I_{CC}$ 10 digits 16 dots/character	—	250	365	mA	$V_{CC}=5.0$ V, “#” displayed in all 10 digits at 100% brightness at 25°C
$I_{IL}$ Input current	—	—	-10	$\mu$ A	$V_{CC}=5.0$ V, $V_{IN}=0$ V (all inputs)
$I_{IH}$ Input current	—	—	10	$\mu$ A	$V_{CC}=V_{IN}=5.0$ V (all inputs)
$V_{IH}$	3.5	—	—	V	$V_{CC}=4.5$ V to 5.5 V
$V_{IL}$	—	—	1.5	V	$V_{CC}=4.5$ V to 5.5 V
$I_{OH}$ (CLK I/O)	—	-8.9	—	mA	$V_{CC}=4.5$ V, $V_{OH}=2.4$ V
$I_{OL}$ (CLK I/O)	—	1.6	—	mA	$V_{CC}=4.5$ V, $V_{OL}=0.4$ V
$\theta_{JA}$	—	—	31	°C/W	—
$F_{ext}$ External Clock Input Frequency	120	—	347	kHz	$V_{CC}=5.0$ V, $\overline{CLKSEL}=0$
$F_{osc}$ Internal Clock Input Frequency	120	—	347	kHz	$V_{CC}=5.0$ V, $\overline{CLKSEL}=1$
Clock I/O Bus Loading	—	—	240	pF	—
Clock Out Rise Time	—	—	500	ns	$V_{CC}=4.5$ V, $V_{OH}=2.4$ V
Clock Out Fall Time	—	—	500	ns	$V_{CC}=4.5$ V, $V_{OH}=0.4$ V
FM, Digit	375	768	1086	Hz	—

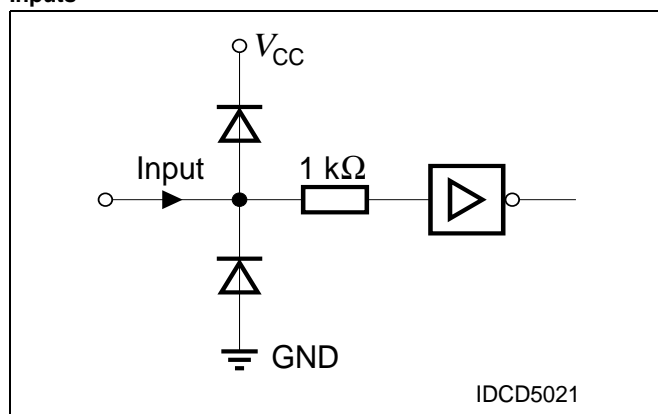
### Notes:

- 1) Peak current  $\frac{5}{3} \times I_{CC}$ .
- 2) Unused inputs must be tied high.
- 3) Contact Infineon for 3.3 V operation.
- 4) External oscillator must be stopped if being used to maintain an  $I_{CC} < 50 \mu$ A.

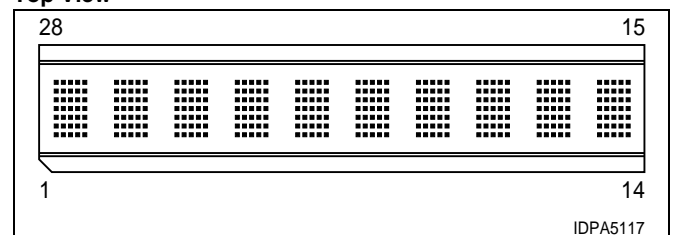
### Input/Output Circuits

Figures „Inputs“ and „Clock I/O“ show the input and output resistor/diode networks used for ESD protection and to eliminate substrate latch-up caused by input voltage over/under shoot.

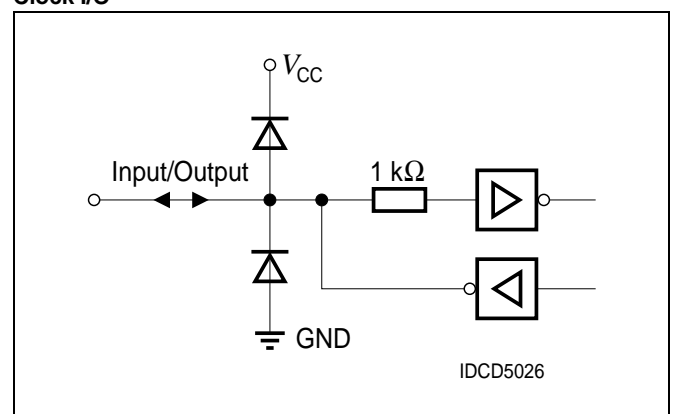
#### Inputs



#### Top View



#### Clock I/O



Pin Assignment

Pin	Function	Pin	Function
1	SDCLK	28	GND
2	$\overline{\text{LOAD}}$	27	DATA
3	NP	26	NP
4	NP	25	NP
5	NP	24	NP
6	NP	23	NP
7	NP	22	NP
8	NP	21	NP
9	NP	20	NP
10	NP	19	$V_{CC}$
11	NP	18	NC
12	NP	17	NP
13	$\overline{\text{RST}}$	16	$\overline{\text{CLKSEL}}$
14	GND	15	CLK I/O

Switching Specifications

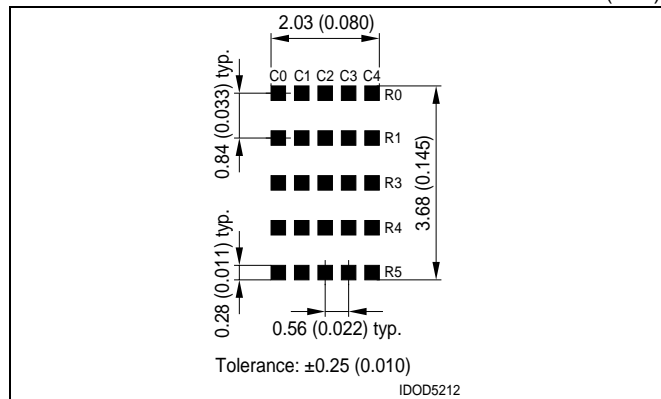
(over operating temperature range and  $V_{CC}=4.5\text{ V to }5.5\text{ V}$ )

Symbol	Description	Min.	Units
$T_{RC}$	Reset Active Time	600	ns
$T_{LDS}$	Load Setup Time	50	ns
$T_{DS}$	Data Setup Time	50	ns
$T_{SDCLK}$	Clock Period	200	ns
$T_{SDCW}$	Clock Width	70	ns
$T_{LDH}$	Load Hold Time	0	ns
$T_{DH}$	Data Hold Time	25	ns
$T_{WR}$	Total Write Time	2.2	$\mu\text{s}$
$T_{BL}$	Time Between Loads	600	ns

Note:  $T_{SDCW}$  is the minimum time the SDCLK may be low or high. The SDCLK period must be a minimum of 200 ns.

Dot Matrix Format

mm (inch)



Pin Definitions

Pin	Function	Definitions
1	SDCLK	Loads data into the 8-bit serial data register on a low to high transition.
2	$\overline{\text{LOAD}}$	Low input enables data clocking into 8-bit serial shift register. When $\overline{\text{LOAD}}$ goes high, the contents of 8-bit serial Shift Register will be decoded.
3	NP	No Pin
4	NP	No Pin
5	NP	No Pin
6	NP	No Pin
7	NP	No pin
8	NP	No pin
9	NP	No Pin
10	NP	No Pin
11	NP	No Pin
12	NP	No Pin
13	$\overline{\text{RST}}$	Asynchronous input, when low will clear the Multiplex Counter, User RAM and Data Register. Control Word Register is set to 100% brightness and the Address Register is set to select Digit 0. The display is blanked.
14	GND	Power supply ground
15	CLK I/O	Outputs master clock or inputs external clock.
16	$\overline{\text{CLKSEL}}$	H=internal clock, L=external clock
17	NP	No Pin
18	NC	No connection
19	$V_{CC}$	Power supply/heat sink
20	NP	No Pin
21	NP	No pin
22	NP	No pin
23	NP	No Pin
24	NP	No Pin
25	NP	No Pin
26	NP	No Pin
27	DATA	Serial data input
28	GND	Power supply ground



The following explains how to format the serial data to be loaded into the display. The user supplies a string of bit mapped decoded characters. The contents of this string is shown in Figure „Loading Serial Character Data a“ (page 8). Figure „Loading Serial Character Data b“ (page 8) shows that each character consist of six 8 bit words. The first word encodes the display character location and the succeeding five bytes are row data. The row data represents the status (On, Off) of individual column LEDs. Figure „Loading Serial Character Data c“ (page 8) shows that each 8 bit word is formatted to include a three bit Operational Code (OPCODE) defined by bits D7–D5 and five bits (D4–D0) representing Column Data, Character Address, or Control Word Data.

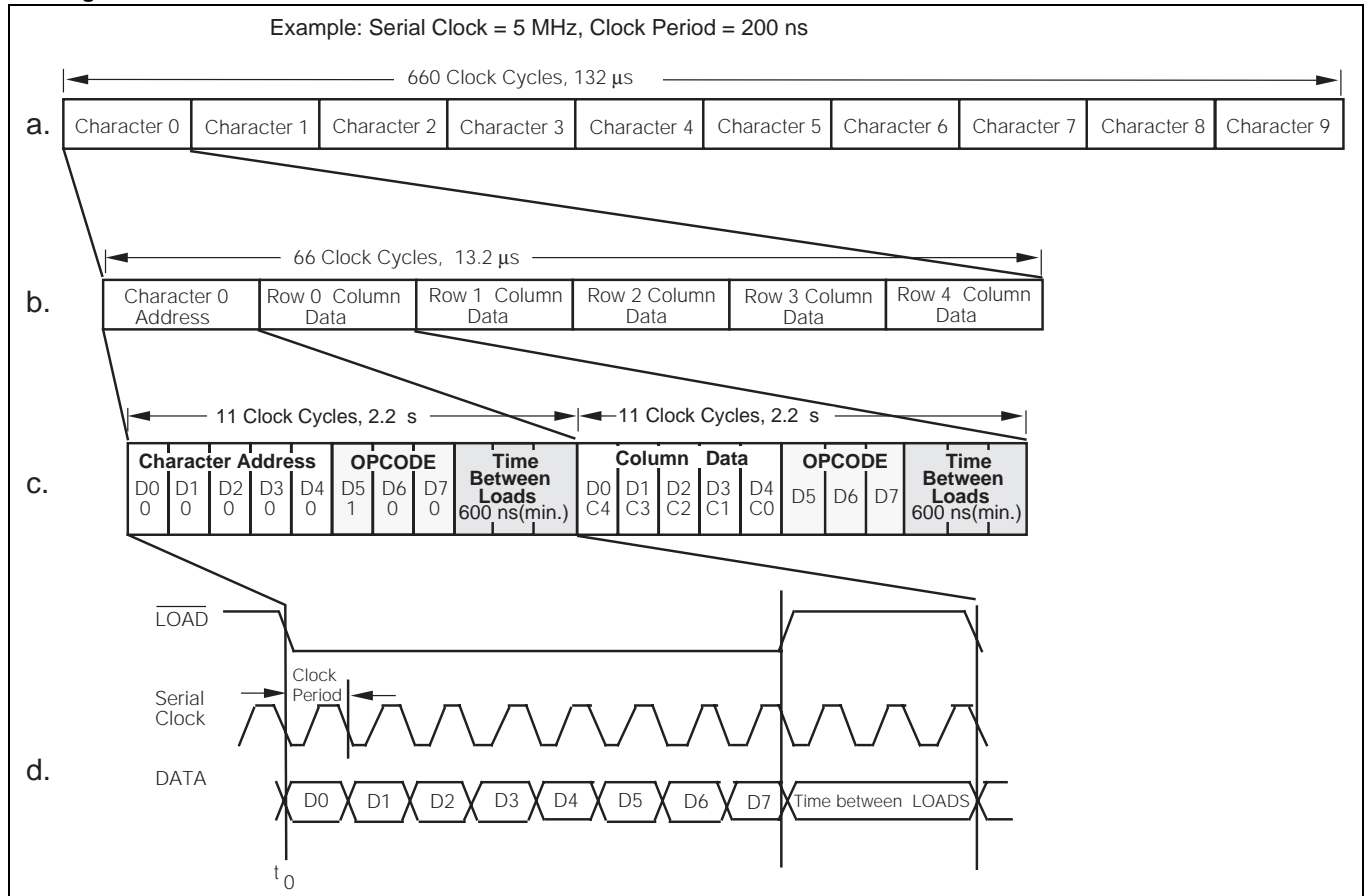
Figure „Loading Serial Character Data d“ (page 8) shows the sequence for loading the bytes of data. Bringing the  $\overline{\text{LOAD}}$  line low enables the serial register to accept data. The shift action occurs on the low to high transition of the serial data clock (SDCLK). The least significant bit (D0) is loaded first. After eight clock pulses the  $\overline{\text{LOAD}}$  line is brought high. With this transition the OPCODE is decoded. The decoded OPCODE directs D4–D0 to be latched in the Character Address register, stored in the RAM as Column data, or latched in the Control Word register. The control IC requires a minimum 600 ns delay between successive byte loads. As indicated in Figure „Loading Serial Character Data a“ (page 8), a total of 660 clock cycles (60-8 bit words) are required to load all ten characters into the display.

The Character Address Register bits, D4–D0 (Table „Load Character Address“ (page 9)) and Row Address Register bits, D7–D5 (Table „Load Column Data“ (page 9)) direct the Column Data bits, D4–D0 (Table „Load Column Data“ (page 9)) to specific RAM location. Table „Character 'D'“ (page 8) shows the Row Address for the example character "D." Column data is written and read asynchronously from the 250 bit RAM. Once loaded the internal oscillator and character multiplexer reads the data from the RAM. These characters are row strobed with column data as shown in Figures „Row and Column Location“ (page 9) and „Row Strobing“ (page 10). The character strobe rate is determined by the internal or user supplied external MUX Clock and the IC's  $\div 320$  counter.

Character "D"

	Op code			Column Data					Hex
	D7	D6	D5	D4 C0	D3 C1	D2 C2	D1 C3	D0 C4	
Row 0	0	0	0	1	1	1	1	0	1E
Row 1	0	0	1	1	0	0	0	1	31
Row 2	0	1	0	1	0	0	0	1	51
Row 3	0	1	1	1	0	0	0	1	71
Row 4	1	0	0	1	1	1	1	0	9E

Loading Serial Character Data





## Load Character Address

Op code D7 D6 D5	Character Address D4 D3 D2 D1 D0	Hex	Operation Load
1 0 1	1 0 0 0 0	B0	Character 0
1 0 1	1 0 0 0 1	B1	Character 1
1 0 1	1 0 0 1 0	B2	Character 2
1 0 1	1 0 0 1 1	B3	Character 3
1 0 1	1 0 1 0 0	B4	Character 4
1 0 1	1 0 1 0 1	B5	Character 5
1 0 1	1 0 1 1 0	B6	Character 6
1 0 1	1 0 1 1 1	B7	Character 7
1 0 1	1 1 0 0 0	B8	Character 8
1 0 1	1 1 0 0 1	B9	Character 9

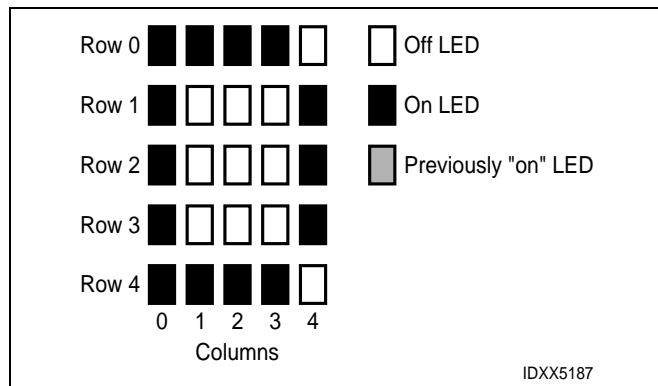
## Load Column Data

Op code D7 D6 D5	Column Data D4 D3 D2 D1 D0	Operation Load
0 0 0	C0 C1 C2 C3 C4	Row 0
0 0 1	C0 C1 C2 C3 C4	Row 1
0 1 0	C0 C1 C2 C3 C4	Row 2
0 1 1	C0 C1 C2 C3 C4	Row 3
1 0 0	C0 C1 C2 C3 C4	Row 4

The user can activate four Control functions. These include: LED Brightness Level, Lamp Test, IC Power Down, or Display Clear. OPCODEs and five bit words are used to initiate these functions. The OPCODEs and Control Words for the Character Address and Loading Column Data are shown in Tables „Load Character Address“ (page 9) and „Load Column Data“ (page 9).

The user can select seven specific LED brightness levels, Table „Display Brightness“ (page 9). These brightness levels (in percentages of full brightness of the display) include: 100% (F0<sub>HEX</sub>), 53% (F1<sub>HEX</sub>), 40% (F2<sub>HEX</sub>), 27% (F3<sub>HEX</sub>), 20% (F4<sub>HEX</sub>), 13% (F5<sub>HEX</sub>), and 6.6% (F6<sub>HEX</sub>). The brightness levels are controlled by changing the duty factor of the row strobe pulse.

## Row and Column Location



## Display Brightness

Op code D7 D6 D5	Control Word D4 D3 D2 D1 D0	Hex	Operation Level
1 1 1	1 0 0 0 0	F0	100%
1 1 1	1 0 0 0 1	F1	53%
1 1 1	1 0 0 1 0	F2	40%
1 1 1	1 0 0 1 1	F3	27%
1 1 1	1 0 1 0 0	F4	20%
1 1 1	1 0 1 0 1	F5	13%
1 1 1	1 0 1 1 0	F6	6.6%

The SCD5510XA offers a unique Display Power Down feature which reduces  $I_{CC}$  to less than 50  $\mu$ A. When FF<sub>HEX</sub> is loaded, as shown in Table „Power Down“ (page 9), the display is set to 0% brightness and the internal multiplex clock is stopped. When in the Power Down mode data may still be written into the RAM. The display is reactivated by loading a new Brightness Level Control Word into the display.

## Power Down

Op code D7 D6 D5	Control Word D4 D3 D2 D1 D0	Hex	Operation Level
1 1 1	1 1 1 1 1	FF	0% brightness

The Lamp Test is enabled by loading F8<sub>HEX</sub>, Table „Lamp Test“ (page 9), into the serial shift register. This Control Word sets all of the LEDs to a 53% brightness level. Operation of the Lamp Test has no effect on the RAM and is cleared by loading a Brightness Control Word.

## Lamp Test

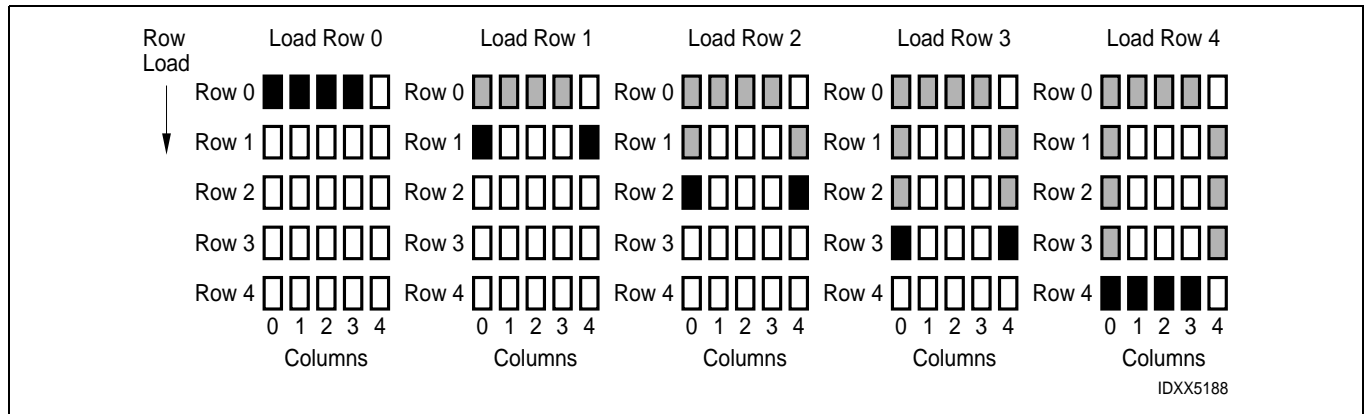
Op code D7 D6 D5	Control Word D4 D3 D2 D1 D0	Hex	Operation Level
1 1 1	1 0 B B B		Lamp Test (OFF)
1 1 1	1 1 0 0 1	F8	Lamp Test (OFF)

The Software Clear (C0<sub>HEX</sub>), given in Table „Software Clear“ (page 9), clears the Address Register and the RAM. The display is blanked and the Character Address Register will be set to Character 0. The internal counter and the Control Word Register are unaffected. The Software Clear will remain active until the next data input cycle is initiated.

## Software Clear

Op code D7 D6 D5	Control Word D4 D3 D2 D1 D0	Hex	Operation Level
1 1 0	0 0 0 0 0	C0	CLEAR

**Row Strobing**



**Multiplexer and Display Driver**

The ten characters are row multiplexed with RAM resident column data. The strobe rate is established by the internal or external MUX Clock rate. The MUX Clock frequency is divided by a 320 counter chain. This results in a typical strobe rate of 750 Hz. By pulling the Clock SEL line low, the display can be operated from an external MUX Clock. The external clock is attached to the CLK I/O connection (pin 15). The maximum external MUX Clock frequency should be limited to 1.0 MHz.

An asynchronous hardware Reset (pin 13) is also provided. Bringing this pin low will clear the Character Address Register, Control Word Register, RAM, and blanks the display. This action leaves the display set at Character Address 0, and the Brightness Level set at 100%.

**Electrical & Mechanical Considerations**

**Interconnect Considerations**

Optimum product performance can be had when the following electrical and mechanical recommendations are adopted. The SCD5510XA's IC is constructed in a high speed CMOS process, consequently high speed noise on the SERIAL DATA, SERIAL DATA CLOCK,  $\overline{\text{LOAD}}$  and  $\overline{\text{RESET}}$  lines may cause incorrect data to be written into the serial shift register. Adhere to transmission line termination procedures when using fast line drivers and long cables (>10 cm).

Good digital grounds (pins 14, 28) and power supply decoupling (pins 6, 9, 20, 23) will insure that  $I_{CC}$  (<400 mA peak) switching currents do not generate localized ground bounce. Therefore it is recommended that each display package use a 0.1  $\mu\text{F}$  and 20  $\mu\text{F}$  capacitor between  $V_{CC}$  and ground.

When the internal MUX Clock is being used connect the  $\overline{\text{CLKSEL}}$  pin to  $V_{CC}$ . In those applications where  $\overline{\text{RESET}}$  will not be connected to the system's reset control, it is recommended that this pin be connected to the center node of a series 0.1  $\mu\text{F}$  and 100 k $\Omega$  RC network. Thus upon initial power up the  $\overline{\text{RESET}}$  will be held low for 10 ms allowing adequate time for the system power supply to stabilize.

The SCD5510XA allows up to 1.7 W of power dissipation at 70° and 1.29 W power dissipation at a maximum operating temperature of 85°C. Approximately 60% of this power is dissipated by the IC to the PC board via the  $V_{CC}$  connection (pins 6, 9, 20, 23). Optimum thermal reliability is obtained by connecting all of the  $V_{CC}$  pins to a common pad located on both sides of the PC board. This technique offers a low thermal resistance for IC to system ambient.

**ESD Protection**

The input protection structure of the SCD55100A/1A/2A/3A/4A provides significant protection against ESD damage. It is capable of withstanding discharges greater than 2.0 kV. Take all the standard precautions, normal for CMOS components. These include properly grounding personnel, tools, tables, and transport carriers that come in contact with unshielded parts. If these conditions are not, or cannot be met, keep the leads of the device shorted together or the parts in anti-static packaging.

**Soldering Considerations**

The SCD55100A/1A/2A/3A/4A can be hand soldered with SN63 solder using a grounded iron set to 260°C.

Wave soldering is also possible following these conditions: Pre-heat that does not exceed 93°C on the solder side of the PC board or a package surface temperature of 85°C. Water soluble organic acid flux (except carboxylic acid) or rosin-based RMA flux without alcohol can be used.

Wave temperature of 245°C  $\pm$  5°C with a dwell between 1.5 sec. to 3.0 sec. Exposure to the wave should not exceed temperatures above 260°C for five seconds at 1.59 mm (0.063") below the seating plane. The packages should not be immersed in the wave.

**Post Solder Cleaning Procedures**

The least offensive cleaning solution is hot D.I. water (60°C) for less than 15 minutes. Addition of mild saponifiers is acceptable. Do not use commercial dishwasher detergents.

For faster cleaning, solvents may be used. Exercise care in choosing solvents as some may chemically attack the nylon package. Maximum exposure should not exceed two minutes at elevated temperatures. Acceptable solvents are TF (trichlorotrifluorethane), TA, 111 Trichloroethane, and unheated acetone.<sup>(1)</sup>

Note:

- <sup>1)</sup> Acceptable commercial solvents are: Basic TF, Arklone, P. Genesolv, D. Genesolv DA, Blaco-Tron TF and Blaco-Tron TA.

Unacceptable solvents contain alcohol, methanol, methylene chloride, ethanol, TP35, TCM, TMC, TMS+, TE, or TES. Since many commercial mixtures exist, contact a solvent vendor for chemical composition information. Some major solvent manufacturers are: Allied Chemical Corporation, Specialty Chemical Division, Morristown, NJ; Baron-Blakeslee, Chicago, IL; Dow Chemical, Midland, MI; E.I. DuPont de Nemours & Co., Wilmington, DE.

# SCD55100A, SCD55101A, SCD55102A, SCD55103A, SCD55104A

For further information refer to Appnotes 18 and 19 at [www.osram-os.com](http://www.osram-os.com)

An alternative to soldering and cleaning the display modules is to use sockets. Naturally, 28 pin DIP sockets 7.62 mm (0.300") wide with 2.54 mm (0.100") centers work well for single displays. Multiple display assemblies are best handled by longer SIP sockets or DIP sockets when available for uniform package alignment. Socket manufacturers are Aries Electronics, Inc., Frenchtown, NJ; Garry Manufacturing, New Brunswick, NJ; Robinson-Nugent, New Albany, IN; and Samtec Electronic Hardware, New Albany, IN.

For further information refer to Appnote 22 at [www.osram-os.com](http://www.osram-os.com)

## Optical Considerations

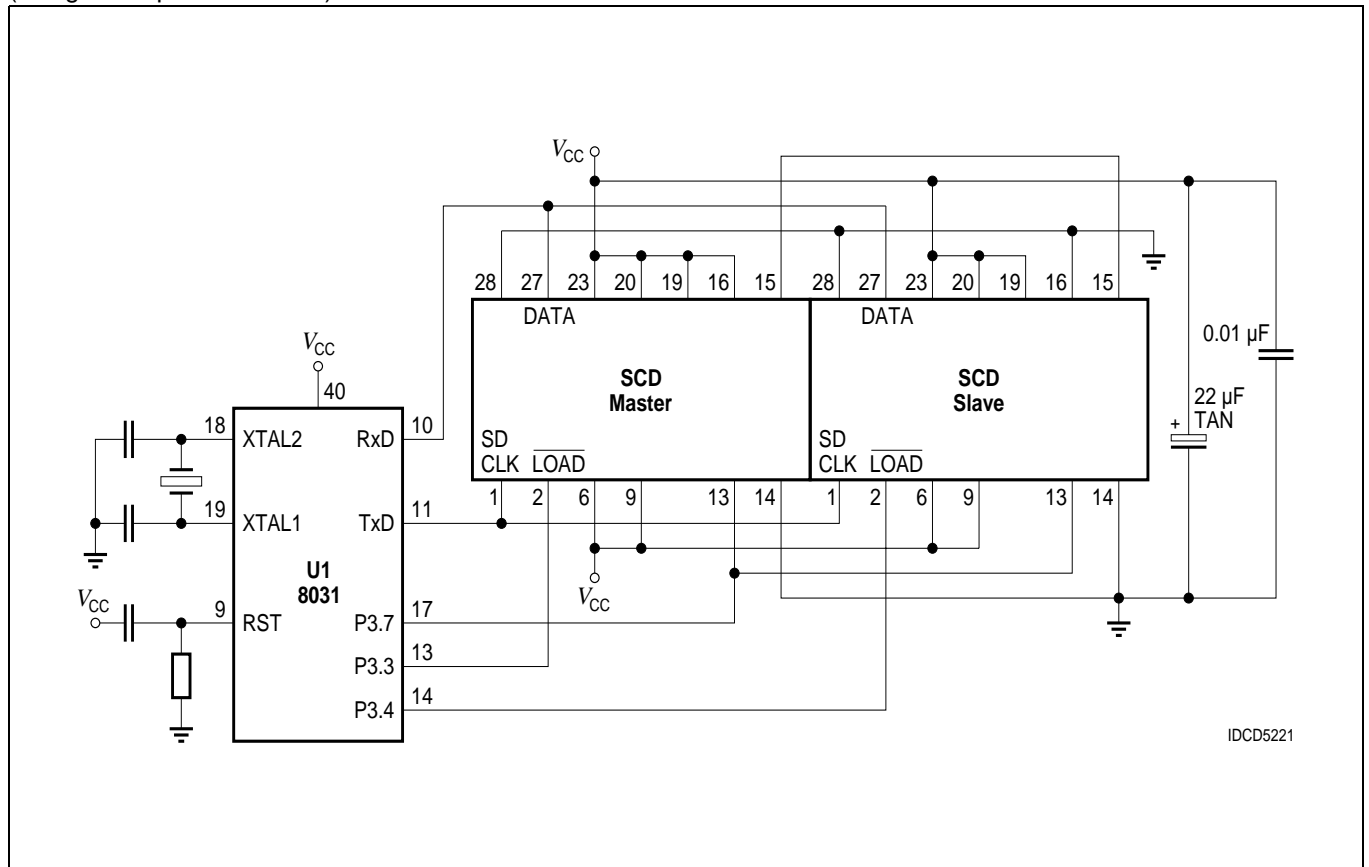
The 3.683 mm (0.145") high character of the SCD5510XA gives readability up to eight feet. Proper filter selection enhances readability over this distance.

Using filters emphasizes the contrast ratio between a lit LED and the character background. This will increase the discrimination of different characters. The only limitation is cost. Take into consideration the ambient lighting environment for the best cost/benefit ratio for filters.

Incandescent (with almost no green) or fluorescent (with almost no red) lights do not have the flat spectral response of sunlight. Plastic band-pass filters are an inexpensive and effective way to strengthen contrast ratios. The SCD5510A/2A are red/high efficiency red displays and should be matched with long wavelength pass filter in the 570 nm to 590 nm range. The SCD55103A/4A should be matched with a yellow-green band-pass filter that peaks at 565 nm. For displays of multiple colors, neutral density grey filters offer the best compromise.

## SCD Interface with Siemens/Intel 8031 Microprocessor

(using serial port in mode 0)



# SCD55100A, SCD55101A, SCD55102A, SCD55103A, SCD55104A

Additional contrast enhancement is gained by shading the displays. Plastic band-pass filters with built-in louvers offer the next step up in contrast improvement. Plastic filters can be improved further with anti-reflective coatings to reduce glare. The trade-off is fuzzy characters. Mounting the filters close to the display reduces this effect. Take care not to overheat the plastic filter by allowing for proper air flow.

Optimal filter enhancements are gained by using circular polarized, anti-reflective, band-pass filters. The circular polarizing further enhances contrast by reducing the light that travels through the filter and reflects back off the display to less than 1%.

Several filter manufacturers supply quality filter materials. Some of them are: Panelgraphic Corporation, W. Caldwell, NJ; SGL Homalite, Wilmington, DE; 3M Company, Visual Products Division, St. Paul, MN; Polaroid Corporation, Polarizer Division, Cambridge, MA; Marks Polarized Corporation, Deer Park, NY; Hoya Optics, Inc., Fremont, CA.

One last note on mounting filters: recessing displays and bezel assemblies is an inexpensive way to provide a shading effect in overhead lighting situations. Several Bezel manufacturers are: R.M.F. Products, Batavia, IL; Nobex Components, Griffith Plastic Corp., Burlingame, CA; Photo Chemical Products of California, Santa Monica, CA; I.E.E.-Atlas, Van Nuys, CA.

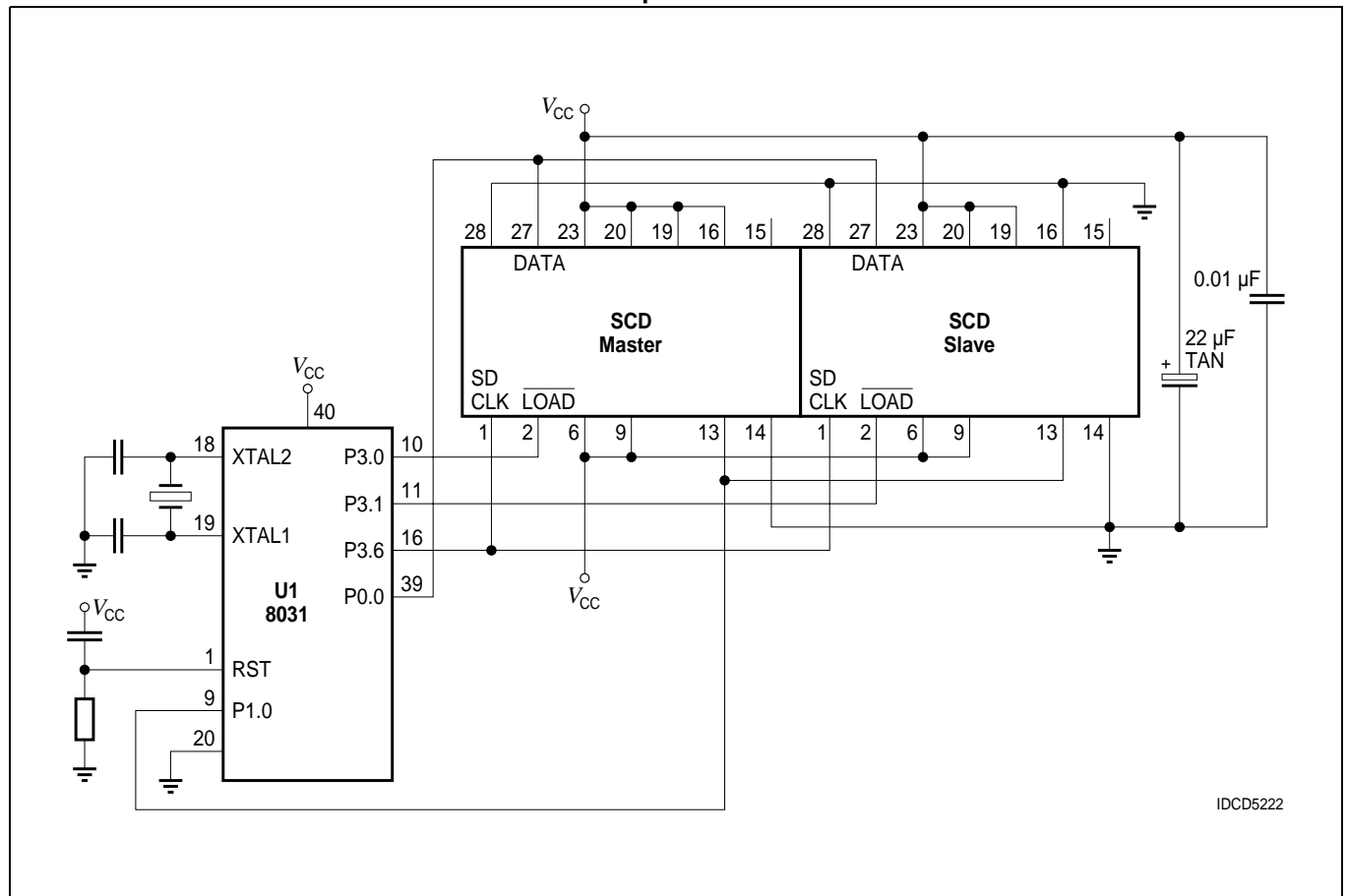
## Microprocessor Interface

The microprocessor interface is through the serial port, SPI port or one out of eight data bits on the eight bit parallel port and also control lines  $\overline{SDCLK}$  and  $\overline{LOAD}$ .

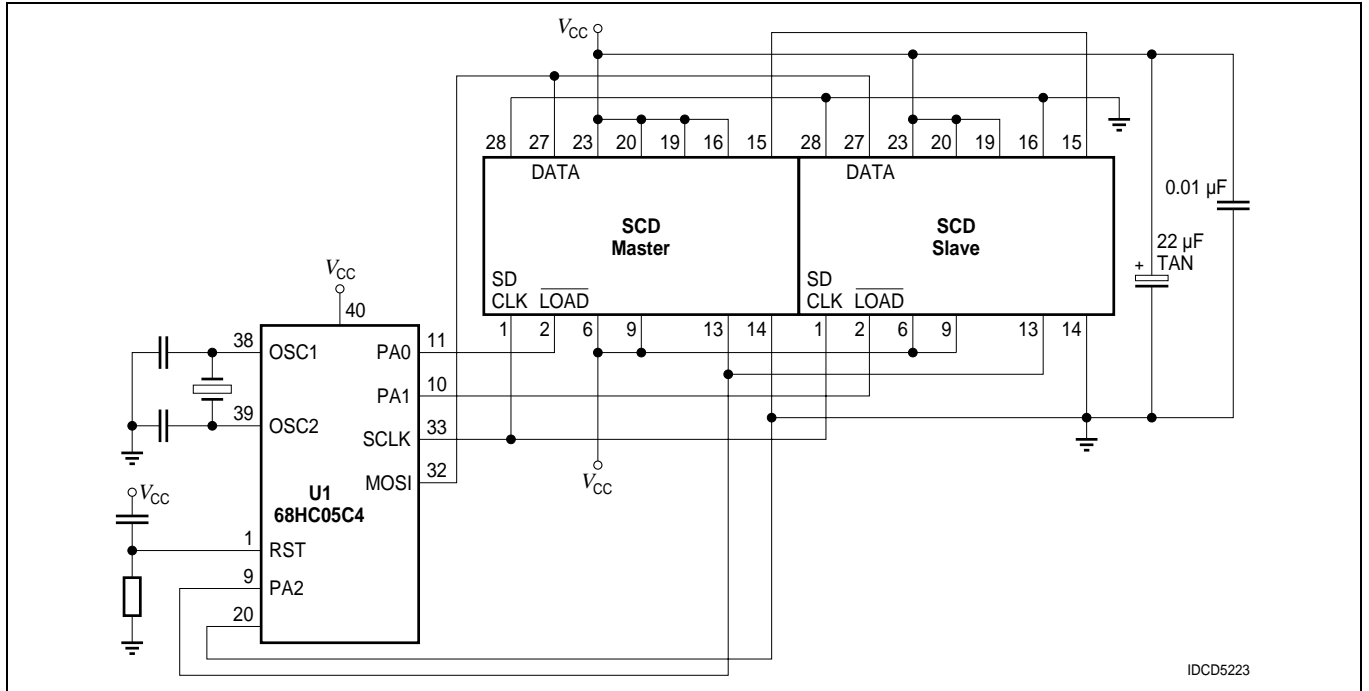
## Power Up Sequence

Upon power up display will come on at random. Thus the display should be reset at power-up. The reset will set the Address Register to Digit 0, User RAM is set to 0 (display blank) the Control Word is set to 0 (100% brightness with Lamp Test off) and the internal counters are reset.

## SCD5510XA Interface with Siemens/Intel 8031 Microprocessor



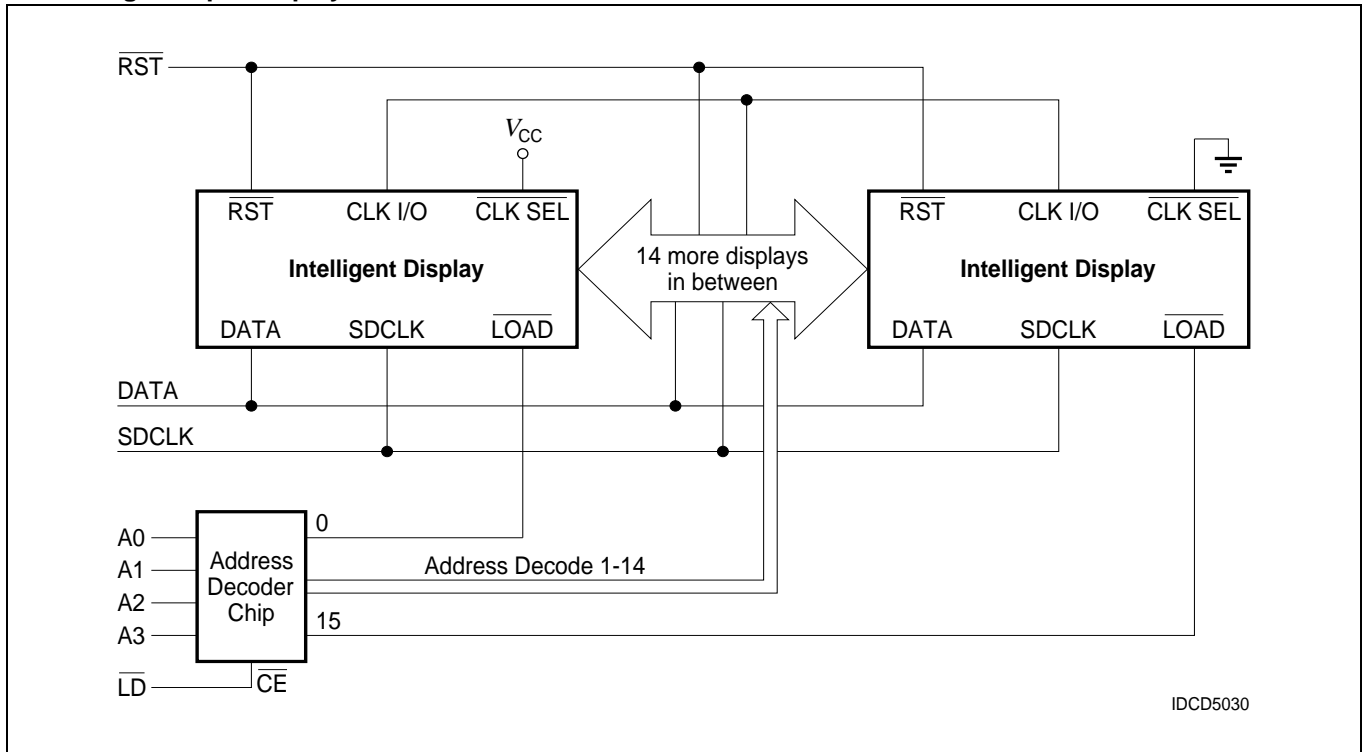
**SCD5510XA Interface with Motorola 68HC05C4 Microprocessor**  
(using SPI port)



**Cascading Multiple Displays**

Multiple displays can be cascaded using the  $\overline{\text{CLKSEL}}$  and CLK I/O pins as shown below. The display designated as the Master Clock source should have its CLKSEL pin tied high and the slaves should have their CLKSEL pins tied low. All CLK I/O pins should be tied together. One display CLK I/O can drive 15 slave CLK I/Os. Use RST to synchronize all display counters.

**Cascading Multiple Displays**



# SCD55100A, SCD55101A, SCD55102A, SCD55103A, SCD55104A

## Loading Data Into the Display

Use following procedure to load data into the display:

1. Power up the display.
2. Bring  $\overline{\text{RST}}$  low (600 ns duration minimum) to clear the Multiplex Counter, Address Register, Control Word Register, User Ram and Data Register. The display will be blank. Display brightness is set to 100%.
3. If a different brightness is desired, load the proper brightness opcode into the Control Word Register.
4. Load the Digit Address into the display.
5. Load display row and column data for the selected digit.
6. Repeat steps 4 and 5 for all digits.

## Data Contents for the Word "Displays"

Step	D7	D6	D5	D4	D3	D2	D1	D0	Function
A	1	1	0	0	0	0	0	0	CLEAR
B (optional)	1	1	1	1	0	B	B	B	BRIGHTNESS SELECT
1	1	0	1	1	0	0	0	0	DIGIT D0 SELECT
2	0	0	0	1	1	1	1	0	ROW 0 D0 (D)
3	0	0	1	1	0	0	0	1	ROW 1 D0 (D)
4	0	1	0	1	0	0	0	1	ROW 2 D0 (D)
5	0	1	1	1	0	0	0	1	ROW 3 D0 (D)
6	1	0	0	1	1	1	1	0	ROW 4 D0 (D)
7	1	0	1	1	0	0	0	1	DIGIT D1 SELECT
8	0	0	0	0	1	1	1	0	ROW 0 D1 (I)
9	0	0	1	0	0	1	0	0	ROW 1 D1 (I)
10	0	1	0	0	0	1	0	0	ROW 2 D1 (I)
11	0	1	1	0	0	1	0	0	ROW 3 D1 (I)
12	1	0	0	0	1	1	1	0	ROW 4 D1 (I)
13	1	0	1	1	0	0	1	0	DIGIT D2 SELECT
14	0	0	0	0	1	1	1	1	ROW 0 D2 (S)
15	0	0	1	1	0	0	0	0	ROW 1 D2 (S)
16	0	1	0	0	1	1	1	0	ROW 2 D2 (S)
17	0	1	1	0	0	0	0	1	ROW 3 D2 (S)
18	1	0	0	1	1	1	1	0	ROW 4 D2 (S)
19	1	0	1	1	0	0	1	1	DIGIT D3 SELECT
20	0	0	0	1	1	1	1	0	ROW 0 D3 (P)
21	0	0	1	1	0	0	0	1	ROW 1 D3 (P)
22	0	1	0	1	1	1	1	0	ROW 2 D3 (P)
23	0	1	1	1	0	0	0	0	ROW 3 D3 (P)
24	1	0	0	1	0	0	0	0	ROW 4 D3 (P)
25	1	0	1	1	0	1	0	0	DIGIT D4 SELECT
26	0	0	0	1	0	0	0	0	ROW 0 D4 (L)
27	0	0	1	1	0	0	0	0	ROW 1 D4 (L)
28	0	1	0	1	0	0	0	0	ROW 2 D4 (L)
29	0	1	1	1	0	0	0	0	ROW 3 D4 (L)
30	1	0	0	1	1	1	1	1	ROW 4 D4 (L)
31	1	0	1	1	0	1	0	1	DIGIT D5 SELECT
32	0	0	0	0	0	1	0	0	ROW 0 D5 (A)
33	0	0	1	0	1	0	1	0	ROW 1 D5 (A)
34	0	1	0	1	1	1	1	1	ROW 2 D5 (A)
35	0	1	1	1	0	0	0	1	ROW 3 D5 (A)
36	1	0	0	1	0	0	0	1	ROW 4 D5 (A)
37	1	0	1	1	0	1	1	0	DIGIT D6 SELECT
38	0	0	0	1	0	0	0	1	ROW 0 D6 (Y)
39	0	0	1	0	1	0	1	0	ROW 1 D6 (Y)
40	0	1	0	0	0	1	0	0	ROW 2 D6 (Y)
41	0	1	1	0	0	1	0	0	ROW 3 D6 (Y)
42	1	0	0	0	0	1	0	0	ROW 4 D6 (Y)
43	1	0	1	1	0	1	1	1	DIGIT D7 SELECT
44	0	0	0	0	1	1	1	1	ROW 0 D7 (S)
45	0	0	1	1	0	0	0	0	ROW 1 D7 (S)
46	0	1	0	0	1	1	1	0	ROW 2 D7 (S)
47	0	1	1	0	0	0	0	1	ROW 3 D7 (S)
48	1	0	0	1	1	1	1	0	ROW 4 D7 (S)

Note:

If the display is already reset at Power Up, there is no need for Software Clear.







**Revision History: 2008-07-22**

Previous Version: 2006-02-20

<b>Page</b>	<b>Subjects (major changes since last revision)</b>	<b>Date of change</b>
all	Lead free device	2006-01-23
6	Pin assignment corrected	2008-07-22

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